

REMARKS/ARGUMENTS**1. Amendment to claim 1:**

Claim 1 is amended to limit that the third conductive layer and the fifth conductive layer are made by a same patterned layer. In para. [0023] of the applicant's invention mentioned that the third conductive layer 126 and the fifth conductive layer 138 are formed by patterning a same metal layer. So, the amended claim 1 is supported by the specification. And, no new matter is introduced. Reconsideration of the amended claim 1 is politely requested.

2. Regarding the Advisory action, dated 06/02/2006:

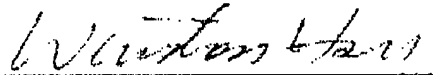
The amended claim1 is different from APA in view of Ikeda et al. (US 5,182,661). The third conductive layer 126 and the fifth conductive layer 138 of the applicant's invention are made by a same patterned layer. Because the applicant's invention only needs one metal layer and one patterned step for forming the third and fifth conductive layer, the applicant's invention saves time and cost of the manufacture, and simplifies the processes. Furthermore, the third conductive layer 126 is not connected to the fifth conductive layer 138 and the problem of short circuits between the first capacitor, the second capacitor, and the third capacitor will not occur (that is mentioned in para. [0023]).

But, in Ikeda et al. (US 5,182,661), the fifth conductive layer 22 and the third conductive layer 62 are not configured into a same metal layer, and the fifth conductive layer 22 and the fourth conductive layer 22 are the same metal layer. Thus, it is clear that the fifth conductive layer 138 of the applicant's invention is different from the fifth conductive layer 22 of the APA in view of Ikeda et al. (US 5,182,661). The structure and the manufacture of the applicant's invention are different from the APA in view of Ikeda et al. (US 5,182,661).

Thus, the amended claim 1 is patentably distinguishable from APA in view of Ikeda et al. (US 5,182,661). Reconsideration of the amended claims is politely requested.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

5 Sincerely yours,



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15 D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)